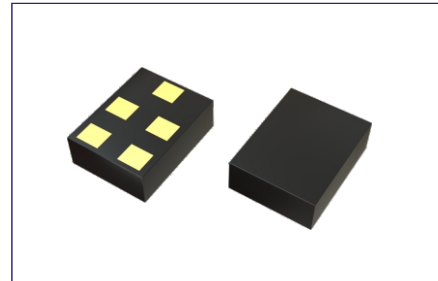
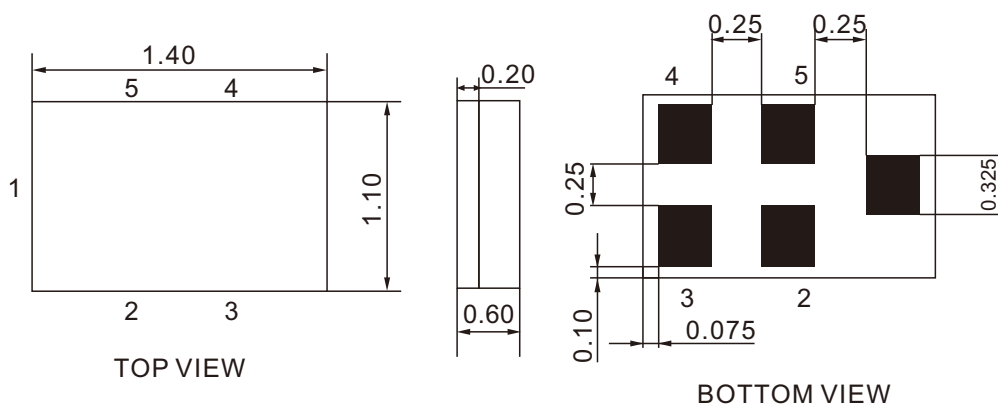


SMD 1.4X1.1X0.6 CSP PACKAGE
PRODUCT FEATURES

- Ultra Small size 1.4x1.1x0.6mm
- CSP process with chip scale package
- Standardization of small size
- Good stability and high reliability
- Mainly used in GPS navigation
- TDD/FDD communication and artificial intelligence chips
- ROHS compliant

PRODUCT PHOTO

PRODUCT SPECIFICATIONS

| Item | | Specifications | Unit |
|-----------------------------|-------|-------------------------------|------|
| Frequency Range | f_c | 800~3600MHz | MHz |
| Standard Frequency | | 1575.42, 1582.4, 1568, 2655 | MHz |
| Useful Band Width | | 3, 18, 48 or specify | MHz |
| Insertion Loss (min) | IL | 0.9, 1.3, 1.8, 2.2 or specify | dB |
| VSWR(max) | | 2.0 | dB |
| Operating Temperature Range | | -40~+85 | °C |
| Storage Temperature Range | | -40~+85 | °C |

PACKAGE OUTLINE / DIMENSIONS


| Pin No. | Description |
|--------------|----------------|
| 1 | Input |
| 4 | Output |
| 2,3,5 | To be grounded |

单击下面可查看定价，库存，交付和生命周期等信息

[>>HCI\(杭晶\)](#)